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JPW

Att. Docket No. 10191/1629

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. Serial No. : 09/720,761 Confirmation No. 5642
Title : METHOD OF PLASMA ETCHING OF SILICON
Applicant(s) : Franz LAERMER et al.
Filed : March 26, 2001
TC/A.U. : 1765
Examiner : Kin Chan Chen
Docket No. : 10191/1629
Customer No. : 26646

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

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TRANSMITTAL OF REPLACEMENT AMENDMENT

SIR:

Transmitted herewith for filing in the above-identified patent application is a
Replacement Amendment for the Amendment filed March 31, 2004 (and mailed on March
29, 2004).

While no fee is believed to be due (since this Replacement Amendment is being filed
within one month of the Notice of Non-Compliant Amendment mailed on April 13, 2004),
the Commissioner is authorized to charge payment of any fees (including any extension fees)
associated with this communication or credit any overpayment to the deposit account of
Kenyon & Kenyon, deposit account number **11-0600**. A duplicate copy of this page is
enclosed.

Respectfully submitted,

Dated: 5/13/2004

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